

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

Claim 1. (Cancelled).

Claim 2. (Previously presented) The solder deposition method according to claim 8, wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and

providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

Claim 3. (Previously presented) The solder deposition method according to claim 8, wherein said dam is not removed after depositing solder.

Claim 4. (Previously presented) The solder deposition method according to claim 8, wherein said substrate is a via-on-pad structured substrate.

Claims 5-7. (Cancelled).

Claim 8. (Currently Amended) A solder deposition method comprising the steps of: forming a dam around an electrode on a substrate; applying a solder precipitating composition to said substrate; and depositing heating the resulting substrate so as to deposit solder on the surface of said electrode while heating said solder precipitating composition applied,

wherein said solder precipitating composition comprises a tin powder; and a complex of at least one member selected from the group consisting of silver ions and copper ions, and at

least one member selected from the group consisting of aryl phosphines, alkyl phosphines and azoles.

Claim 9. (Currently amended) A solder deposition method comprising the steps of:
forming a dam around an electrode on a substrate;
applying a solder precipitating composition to said substrate; and
depositing heating the resulting substrate so as to deposit solder on the surface of said electrode while heating said solder precipitating composition applied,
wherein said solder precipitating composition comprises a tin powder and a salt of at least one metal selected from the group consisting of lead, copper and silver.

Claim 10. (Previously presented) The solder deposition method according to claim 9,
wherein said step of forming a dam includes the steps of:
forming a resin film on the surface of said substrate; and
providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

Claim 11. (Previously presented) The solder deposition method according to claim 9,
wherein said dam is not removed after depositing solder.

Claim 12. (Previously presented) The solder deposition method according to claim 9,
wherein said substrate is a via-on-pad structured substrate.